

High Performance Plastic
SUMIKASUPER™ LCP

*E5000, E4000, E6000, E6000HF,
SV6000, SZ, and SR Series
Product Selector*

LIQUID CRYSTAL POLYMER

Sumitomo Chemical Environmental, Social and Governance (ESG) Initiatives and Recognitions

Active participation in a variety of global initiatives that help promote environmental, societal, and business sustainability is an important principle of the Sumitomo Chemical Group. Therefore, we work with a broad range of organizations at the international, national, and local level, as well as industry groups.

We were the first Japanese company to join the United Nation's Global Compact (UNGC) in January 2005. As a good member of society regularly demonstrating responsible and creative leadership, we have been named as one of only 41 UN Global Compact LEAD companies in the world for our constant engagement with the UNGC and compliance with the group's 10 principles related to protecting human rights and the environment, abolishing unfair labor practices, and preventing corruption.

We are proud to participate in initiatives like the following below.



We
Support



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SUMIKASUPER™ LCP General Property Benefits

SUMIKASUPER liquid crystal polymers (LCPs) are a family of thermotropic, fully aromatic, liquid crystalline polyesters that possess the highest heat resistance among engineering thermoplastics.

Polyester-based LCPs are known for their excellent electrical properties¹, high-thermal stability and mechanical performance, inherent flame retardance², broad chemical resistance³, high resistance to stress cracking, and good weatherability. This makes SUMIKASUPER LCPs ideal for use in:

- **Electrical and electronic components** including fiberoptic cables, printed circuit boards (PCBs), chip carriers, connectors (conventional, radio-frequency (RF), and fiber-optic), CPU sockets, relay parts, various bobbins, and other surface-mount components;
- **Office-equipment** parts for printers, faxes, copiers, etc.;
- **Automotive parts** including components for ignition and transmission systems, lamp sockets, pump components, coil forms, and sensors;
- **Non-stick bakeware**;
- **Sterilizable medical devices and drug-delivery devices**;
- **Microelectromechanical systems (MEMS)**;
- **High-barrier/retort-processed food containers**; and
- **Components for chemical processing** including pumps, meters, and valves.

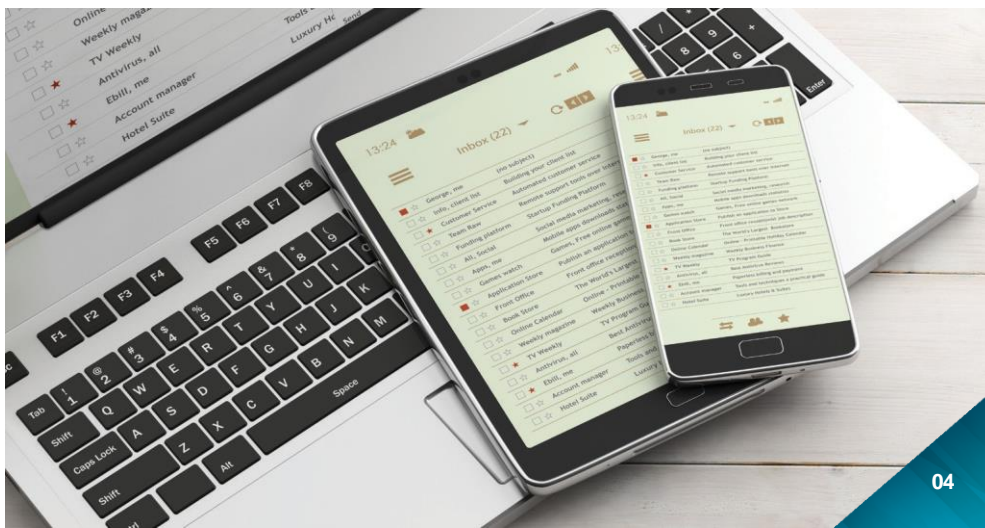
High-performance LCPs are generally processed by injection molding, although they also can be spun into fibers, extruded or cast into sheet and film products, and converted to coatings. A new form of LCPs — the first to be chemically soluble — is used to produce high-performance coatings and films for flexible and rigid electronics and to protect speaker membranes.

A more thorough discussion of general properties, design, and processing recommendations for SUMIKASUPER LCPs can be found at: <https://www.sumitomo-chem.co.jp/sep/english/products/lcp/>.

¹ Electrical properties include high electrical resistivity, low relative permittivity, and low dissipation factor.

² SUMIKASUPER LCPs are considered to be flame-retardant materials and are classified as UL-94 V-0. However, they should be handled and stored well away from places of heat and sources of flames. If the material catches fire, use water, foam, or chemical fire extinguishers to extinguish any flames.

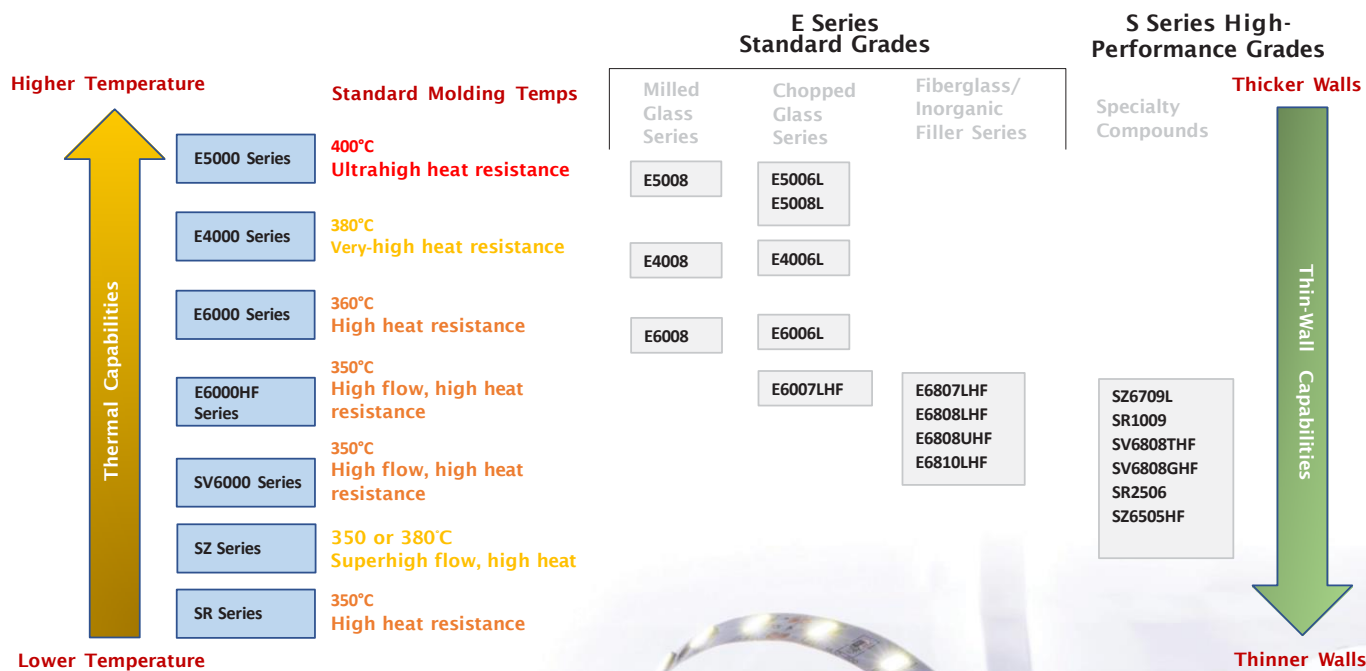
³ Resistance is excellent to strong and weak acids, alcohols, esters, ketones, and aromatic, chlorinated, and halogenated hydrocarbons over a broad range of temperatures. Hydrolytic stability in boiling water also is excellent. LCPs can be attacked by high-temperature steam, concentrated sulfuric acid, and boiling caustic chemicals. A more comprehensive treatment of the chemical resistance of LCPs is shown in Table 1 at https://www.sumitomo-chem.co.jp/sep/english/products/lcp/lcp_bs_kagaku.html



SUMIKASUPER Product Series Overview

Within the SUMIKASUPER family of LCPs, there are 7 major product series: E5000, E4000, E6000, E6000HF, SV6000, SZ, and SR. This section will explain the major differences between those product series and then provide more detail on the grades available within each series. Key attributes and distinguishing features of these series are provided in the table below. Each series will be covered in greater depth in the sections that follow.

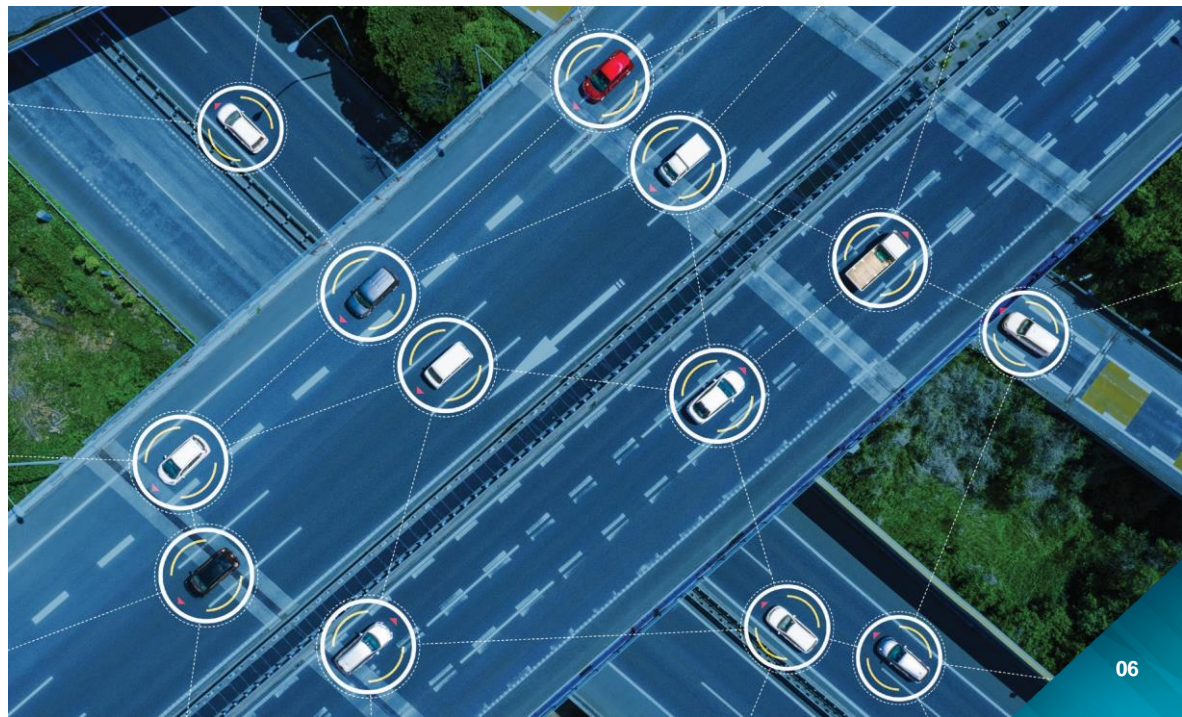
Distinguishing Features Between SUMIKASUPER Product Series



SUMIKASUPER LCP Product Series

Series	General Attributes & Distinguishing Features
Conventional (Standard) Grades	
E5000	Ultrahigh heat resistance Withstands high-temperature reflow soldering High rigidity @ temperatures >200°C
E4000	Very-high heat resistance Withstands high-temperature reflow soldering High rigidity @ temperatures >200°C
E6000	High heat resistance Withstands reflow soldering General-purpose grade
E6000HF	High-flow grades High heat resistance to withstand reflow soldering Ideal for connector applications
Specialty (Value-Added) Grades	
SV6000	High-flow grades High heat resistance to withstand reflow soldering Ideal for connector applications
SZ	Super-high flow High heat resistance Withstands reflow soldering Ideal for connector applications Premium grades with specialty base resins and reinforcements
SR	High heat resistance Withstands reflow soldering Ideal for connector applications Premium grades with specialty base resins and reinforcements

For information on custom-formulated grades, please contact us using the details on the back cover.



SUMIKASUPER E5000 Series

Distinguishing Features

The E5000 Series contains 5 grades: E5006L, E5008, E5008L, E52008, and E5204L.

These materials are distinguished by their ultrahigh heat resistance and ability to maintain stiffness and strength at temperature above 200°C, meaning they can be used for high-temperature surface-mount reflow soldering.

E5000 Series grades are typically processed at 400°C.

Typical Applications / Uses

Most E5000 Series grades are used for injection molded bobbins of various types as well as sealed-cover relays and relay cases, lamp holders/sockets, office printer components, and engine peripheral parts (e.g., insulation board).

Who will be Interested in this Product Series?

Typical companies interested in E5000 Series products include OEMs and molders who produce injection molded components for the electrical/electronic, office-equipment, and automotive markets.

Standard Grades in this Series

All grades in the E5000 Series are available in black (denoted by a B at the end of the grade name) and all but E5204L are also available in natural (off-white).

In addition to standard milled-glass reinforcement (in 30 and 40 wt-%), grades are also available reinforced with high-strength chopped glass fiber (in 30 and 40 wt-%) as well as a low relative permittivity glass fiber with an inorganic filler package (20 wt-%).

E5000 Series Product Offerings

General Properties: Ultrahigh heat resistance; withstands high temperature reflow and dip soldering; high rigidity @ temperature >200°C				
Standard processing temperature: 400°C				
Type of reinforcement	Grade (% reinforcement)	Deflection Temp Under Load (°C)	Additional Characteristics	Typical Applications
Glass fiber	E5006L (30%)	355	Ultrahigh heat resistance, high strength, low coefficient of linear thermal expansion (CLTE), high dimensional accuracy	Optical pick-up bobbin, office equipment, printer parts
	E5008 (40%)	335	Ultrahigh heat resistance, low CLTE	Various polymer & metal bobbins, sealed cover relays
	E5008L (40%)	339	Ultrahigh heat resistance, low mold shrinkage, low CLTE	Lamp holder, sealed relay case/cover, various polymer & metal bobbins, engine peripheral parts (e.g., insulation board)
	E52008 (40%)	336	Ultrahigh heat resistance, good moldability	Various small polymer bobbins
Glass fiber / inorganic filler	E5204L* (20%)	351	Ultrahigh heat resistance, low thermal conductivity, low relative permittivity, thermal insulation	Office equipment parts

* Available in black only. All other grades in this series available in both natural and black (denoted by a B at the end of grade name).

SUMIKASUPER E4000 Series

Distinguishing Features

The E4000 Series contains 4 grades: E4006L, E4008, E4009, and E4205R.

These materials are distinguished by their very-high heat resistance and retention of stiffness and strength at temperature above 200°C, meaning they can be used for high-temperature surface-mount reflow soldering.

E4000 Series grades are typically processed at 380°C.

Typical Applications / Uses

Most E4000 Series grades are used for injection molded bobbins of various types as well as relay cases and other parts, as well as parts for office equipment such as printer components.

Who will be Interested in this Product Series?

Typical companies interested in E4000 Series products include OEMs and molders who produce injection molded components for the electrical/electronic and office-equipment markets.

Standard Grades in this Series

All grades in the E4000 Series are available in natural (off-white) and all but E4009 are also available in black (denoted by a B at the end of the grade name).

In addition to standard milled-glass reinforcement (in 30, 40, and 45 wt-%), grades are also available reinforced with high-strength chopped glass fiber (in 30 and 40 wt-%) as well as a low relative permittivity glass fiber with inorganic filler package (25 wt-%).

E4000 Series Product Offerings

General Properties: Very-high heat resistance; withstands high temperature reflow soldering; high rigidity @ temperature >200°C				
Standard processing temperature: 380°C				
Type of reinforcement	Grade (% reinforcement)	Deflection Temp Under Load (°C)	Additional Characteristics	Typical Applications
Glass fiber	E4006L (30%)	324	High heat, low shrink, lubrication package	Metal terminal bobbins
	E4008 (40%)	326	High heat, high strength sealed relay covers / cases, relay bases	Metal terminal bobbins
	E4009* (45%)	326	High heat, high strength	Relay parts, bobbins
Glass fiber / inorganic filler	E4205R (25%)	305	High heat, low thermal conductivity, low relative permittivity, low loss dielectric constant	Office printer parts

* Available in natural only. All other grades in this series available in both natural and black (denoted by a B at the end of grade name).

SUMIKASUPER E6000 Series

Distinguishing Features

The E6000 Series contains 9 grades: E6006, E6006L, E6008, E6008 KE, E6007AS, E6809U, E6205L, E6807T, and E6809T.

These general-purpose grades are distinguished by their high heat resistance and strength, good moldability and ability to hold tight tolerances, low mold shrinkage, and good mold release. Some E6000 Series grades offer high surface smoothness, one grade (E6007AS) is antistatic, and one grade has low thermal conductivity and permittivity (E6205L).

E6000 Series grades are typically processed at 360°C.

Typical Applications / Uses

Most E6000 Series grades are used for injection molding various connectors, relay parts, coil seals, bobbins, and office printer and automotive parts, plus heat-resistant cookware.

Who will be Interested in this Product Series?

Typical companies interested in E6000 Series products include OEMs and molders who produce injection molded components for the electrical/electronic, office-equipment, automotive, and bakeware markets.

Standard Grades in this Series

All grades in the E6000 Series are available in black (B) and all but E6007AS are also available in natural (off-white).

In addition to standard milled-glass reinforcement (in 30 and 40 wt-%), grades are also available reinforced with high-strength chopped glass fiber (30 wt-%) as well as low-warpage, low anisotropy glass fiber with inorganic filler package (in 35 and 45 wt-%), low warpage, low anisotropy inorganic filler (in 35 and 45 wt-%), and low relative permittivity glass fiber with inorganic filler package (25 wt-%).

E6000 Series Product Offerings

General Properties: High heat resistance, withstands reflow soldering, general-purpose grades				
Standard processing temperature: 360°C				
Type of reinforcement	Grade (% reinforcement)	Deflection Temp Under Load (°C)	Additional Characteristics	Typical Applications
Glass fiber	E6006 (30%)	280	High heat and strength, good moldability, low mold shrinkage, dimensionally precise, high mold-release	Connectors, various bobbins and automotive mechanisms and housings
	E6006L (30%)	284		
Glass fiber / inorganic filler	E6008 (40%)	279	High strength, high moldability, high heat resistance	Relays, bobbins, coil sealing, automotive, lamp sockets
	E6008 KE (40%)	276		
	E6007AS* (35%)	274	Antistatic	Relay parts, various bobbins
	E6809U (45%)	270	Low warpage, high heat resistance, good moldability	Connectors
Inorganic filler	E6205L (25%)	258	Low thermal conductivity, low relative permittivity, high lubricity / low friction	High-frequency connectors, office equipment/printer parts
	E6807T (35%)	262	High surface smoothness	Relay parts, automotive parts, coil sealing
	E6809T (45%)	262	High surface smoothness	Heat-resistant bakeware, connectors

* Available in black only. All other grades in this series available in both natural and black (denoted by a B at the end of grade name).

SUMIKASUPER E6000HF Series

Distinguishing Features

The E6000HF high-flow, low-warpage series contains 8 grades: E6007LHF, E6007LHF-MR, E6807LHF, E6808LHF, E6808GHF, E6808UHF, E6810LHF, and E6810KHF.

These grades are distinguished by their high-flow, low-warpage, and high strength. They also provide high heat resistance to withstand reflow soldering.

E6000HF Series grades are typically processed at 350°C.

Typical Applications / Uses

E6000HF Series grades are especially designed for injection molding a variety of connectors, e.g., memory and memory card, I/O, board-to-board (B2B) fine-pitch connectors, flexible printed circuit (FPC) fine-pitch connectors, as well as relay parts and CPU sockets.

Who will be Interested in this Product Series?

Typical companies interested in E6000HF Series products include OEMs and molders who produce injection molded components for the electrical/electronics markets—particularly connectors.

Standard Grades in this Series

All grades in the E6000HF Series are available in natural and black.

Reinforcement options for grades in this product family include either high-strength chopped glass fiber (35 wt-%) or low-warpage, low-anisotropy glass fiber with inorganic filler packages (35, 40, 50 wt-%) for low mold shrinkage and low anisotropy.

E6000HF Series Product Offerings

General Properties: High flow, high heat resistance, withstands reflow soldering, specially designed for connector applications				
Standard processing temperature: 350°C				
Type of reinforcement	Grade (% reinforcement)	Deflection Temp Under Load (°C)	Additional Characteristics	Typical Applications
Glass fiber	E6007LHF (35%) E6007LHF-MR (35%)	269	Low warpage, high strength, good mold release	Memory connectors, relay parts, B2B fine-pitch connectors, floating connectors
Glass fiber / inorganic filler	E6807LHF (35%)	269	Low warpage, high strength	Memory connectors, CPU sockets
	E6808LHF (40%) E6808GHF (40%) E6808UHF (40%)	274 268 240	Low warpage, high strength, high moldability	I/O connectors, CPU sockets, B2B fine-pitch connectors, FPC fine-pitch connectors, memory connectors, memory-card connectors,
	E6810LHF (50%) E6810KHF (50%)	266 265	Low warpage, low mold shrinkage, low anisotropy	Memory card connectors, I/O connectors

SUMIKASUPER SV6000 Series

Distinguishing Features

The SV6000 Series contains 3 grades: SV6808L, which is typically processed at 360°C and SV6808THF and SV6808GHF, which are typically processed at 350°C.

Typical Applications / Uses

Typically, SV6000 Series grades are used for injection molded connectors (including board-to-board (B-to-B) fine-pitch connectors, flexible printed circuit (FPC) fine-pitch connectors, and memory connectors) as well as CPU sockets.

Who will be Interested in this Product Series?

Typical companies interested in SV6000 Series products include OEMs and molders who produce injection molded connectors and CPU sockets.

Standard Grades in this Series

SV6000 Series grades are available in both natural (off-white) and black (denoted by a B at the end of the grade name).

Grades denoted with an -HF in the name are high flow to enhance moldability in thin wall sections.

These grades are reinforced with a combination of low-warpage, low anisotropy glass fiber and inorganic filler.

SV6000 Series Product Offerings

General Properties: High heat resistance for reflow soldering, -HF grades are high flow				
Standard processing temperature: 350°C or 360°C				
Type of reinforcement	Grade (% reinforcement)	Deflection Temp Under Load (°C)	Additional Characteristics	Typical Applications
Glass fiber / inorganic filler	SV6808L** (40%)	293	Low warpage, high heat resistance, high strength	CPU sockets
	SV6808THF* (40%)	270	Ultralow warpage, high heat resistance, high strength	Double data rate (DDR) memory, board-to-board (B2B) connectors
	SV6808GHF* (40%)	255	Low warpage, high heat resistance, high strength	Thin-wall connectors, B2B fine-pitch connectors, FPC fine-pitch connectors, memory-card connectors

* Processed at 350°C

** Processed at 360°C

SUMIKASUPER SZ Series

Distinguishing Features

The SZ Series consists of 4 grades: SZ6709L, SZ4506, SZ6505HF, and SZ6506HF. SZ6709L, SZ6505HF, and SZ6506HF are typically processed at 350°C while SZ4506 is typically processed at 380°C.

These grades are distinguished by their high heat resistance, enabling them to withstand reflow soldering. They also offer special functional properties, such as ultrahigh flow, moldability, and low warpage (SZ6505HF and SZ6506HF) or high whiteness and high relative permittivity for use as LED reflectors (SZ6709L).

Typical Applications / Uses

Grades in the SZ Series are used in many connector applications (including high-frequency, B-to-B fine-pitch, FPC fine-pitch, and memory-card) as well as LED reflectors.

Who will be Interested in this Product Series?

Typical companies interested in SZ Series products include OEMs and molders who produce injection molded connectors and LED-based lighting systems.

Standard Grades in this Series

All grades in the SZ Series are available in natural (off-white) and all except SZ6709L are also available in black (denoted by a B at the end of the grade name). SZ6709L has been specially formulated for high whiteness and high permittivity for use in LED reflectors.

Grades denoted with an HF in the name are high flow to enhance moldability in thin wall sections.

Three of the grades are reinforced with either 25% or 30% low-warpage, low anisotropy inorganic filler and one grade features both glass fiber and inorganic filler at 45% wt-%.

For information on custom-formulated grades, please contact us using the details on the back cover.

SZ Series Product Offerings

General Properties: High heat resistance for reflow soldering plus functional properties				
Standard processing temperatures: 350°C or 380°C				
Type of reinforcement	Grade (% reinforcement)	Deflection Temp Under Load (°C)	Additional Characteristics	Typical Applications
Glass fiber / inorganic filler	SZ6709L* (45%)	275	High whiteness, high relative permittivity	High-frequency connectors, LED reflectors
Inorganic filler	SZ4506** (30%)	296	Low warpage, high heat resistance, high surface smoothness	Memory card connectors
	SZ6505HF* (25%)	244	Low warpage, ultrahigh moldability	B-to-B fine-pitch connectors, FPC fine-pitch connectors, memory-card connectors, motor insulator
	SZ6506HF* (30%)	245	Low warpage, ultrahigh moldability	B-to-B fine-pitch connectors, FPC fine-pitch connectors, memory-card connectors

Available in natural only. This grade is specially formulated for high whiteness and high permittivity for use in LED reflectors. All other grades in this series available in both natural and black (denoted by a B at the end of grade name).

* Processed at 350°C

** Processed at 360°C

SUMIKASUPER SR Series

Distinguishing Features

The SR Series contains 6 grades: SR1009, SR1009L, SR3003L, SR1205L, SR2506, and SR2507.

SR1009, SR1009L, and SR1205L are distinguished by their high heat resistance, enabling them to withstand reflow soldering. SR1009 provides good moldability and SR1009L provides high hardness. SR1205L offers low relative permittivity and low dielectric dissipation factor. All three grades are typically processed at 360°C.

SR2506 and SR2507 are distinguished by their high heat resistance, enabling them to withstand reflow soldering. Both grades are typically processed at 350°C.

SR3003L offers balanced mechanical properties and good chemical and hydrolysis resistance. It is typically processed at 315°C.

Typical Applications / Uses

SR1009, SR1009L, and SR1205L are used for injection molded flexible printed circuit (FPC) connectors.

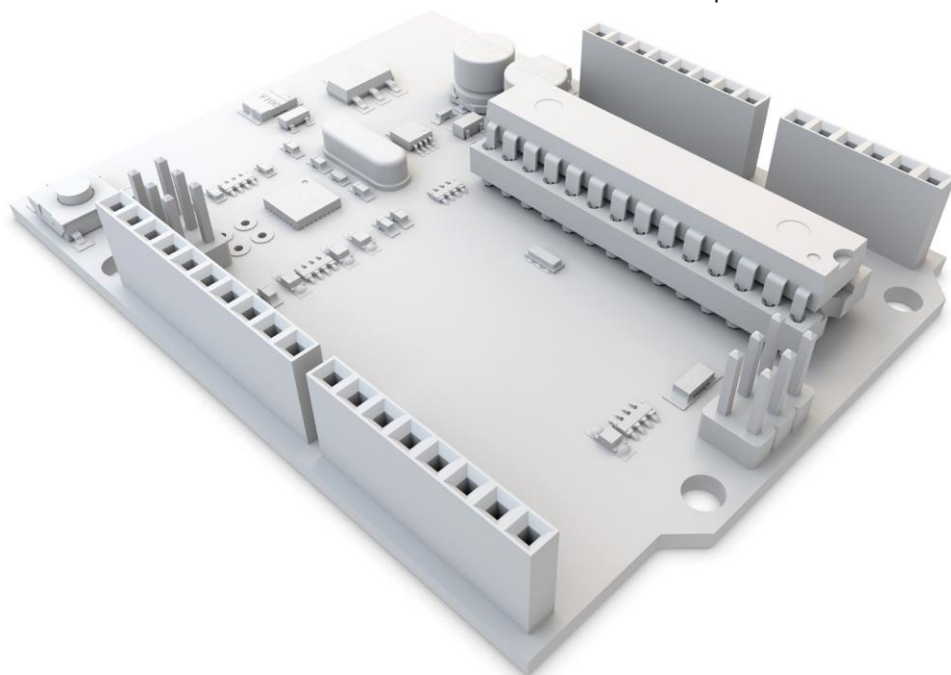
SR2506 and SR2507 are used for injection molded connectors (including board-to-board (B-to-B), fine-pitch, and FPC connectors).

SR3003L is used for medical and drug-delivery devices.

Who will be Interested in this Product Series?

Typical companies interested in SR1009, SR1009L, SR1205L, SR2506, and SR2507 include OEMs and molders who produce injection molded connectors.

Typical companies interested in SR3003L are OEMs and molders who produce medical and drug-delivery devices.



SUMIKASUPER SR Series Continued

Standard Grades in this Series

All grades in the SR Series are available in natural (off-white) and all except SR3003L are also available in black (denoted by a B at the end of the grade name).

SR1009 is reinforced with 45% milled glass fiber for thin-wall molding. SR1009L is reinforced with 45% high-strength chopped glass fiber. SR1205L is reinforced with 25% low-warpage, low anisotropy glass fiber and inorganic filler.

SR2506 is reinforced with 30% low warpage, low anisotropy glass fiber and inorganic filler and offers ultrahigh moldability in thin-wall parts. SR2507 is reinforced with 35% low warpage, low anisotropy inorganic filler and offers ultralow warpage, ultrahigh moldability in thin-wall parts.

SR3003L is reinforced with 15% glass fiber.

SR Series Product Offerings

General Properties: High heat resistance for reflow soldering, low anisotropy				
Standard processing temperature: 315°C or 350°C or 360°C				
Type of reinforcement	Grade (% reinforcement)	Deflection Temp Under Load (°C)	Additional Characteristics	Typical Applications
Glass fiber	SR1009*** (45%)	277	Ultrahigh-intensity, good moldability	FPC connectors
	SR1009L*** (45%)	286	Ultrahigh-intensity, high hardness	FPC connectors
	SR3003L* (15%)	245	Balanced mechanical properties, chemical resistance, good hydrolysis resistance	Medical and drug-delivery devices
Glass fiber / inorganic filler	SR1205L*** (25%)	252	Low relative permittivity, low dielectric dissipation factor	High-frequency connectors, backplane connectors
	SR2506** (30%)	239	Low warpage, ultrahigh moldability in thin-wall parts	B-to-B fine-pitch connectors, FPC fine-pitch connectors
Inorganic filler	SR2507** (35%)	240	Ultralow warpage, ultrahigh moldability in thin-wall parts	B-to-B fine-pitch connectors, FPC fine-pitch connectors

* Processed at 315°C

** Processed at 350°C

*** Processed at 360°C

SUMIKASUPER Liquid Crystal Polymer Properties

Tensile Strength (MPa), ASTM D638

Tensile Elongation at Break (%), ASTM D638

Tensile Modulus (MPa), ISO 527-1,2

Flexural Strength @ 23°C (MPa), ASTM D790

Flexural Modulus @ 23°C (GPa), ASTM D790

Izod Impact Strength -
Unnotched (J/m), ASTM D256

E5000 Series

SUMIKASUPER E5006L	151	4.5	16,600	152	14.2	382
SUMIKASUPER E5008	111	4.8	11,900	127	12.2	441
SUMIKASUPER E5008L	123	3.7	17,000	127	13.4	324

E4000 Series

SUMIKASUPER E4006L	182	5.6	13,700	155	11.9	461
SUMIKASUPER E4008	150	5.0	11,900	139	12.3	520

E6000 Series

SUMIKASUPER E6006	166	7.1	--	127	9.8	490
SUMIKASUPER E6006L	164	5.0	11,500	153	11.3	363
SUMIKASUPER E6008	147	5.2	11,800	143	12.3	412
SUMIKASUPER E6807T	106	6.0	6,500	97	7.3	515

E6000HF Series

SUMIKASUPER E6007LHF	157	5.1	12,500	158	11.8	251
SUMIKASUPER E6007LHF-MR	157	5.1	12,500	158	11.8	251
SUMIKASUPER E6807LHF	135	5.3	11,700	145	12.1	335
SUMIKASUPER E6808LHF	127	4.5	12,600	146	11.8	302
SUMIKASUPER E6808UHF	100	5.0	7,400	120	9.4	350
SUMIKASUPER E6810LHF	105	4.0	12,100	133	12.6	200

SV6000 Series

SUMIKASUPER SV6808THF	110	5.5	10,400	137	9.0	404
SUMIKASUPER SV6808GHF	107	6.2	10,700	127	10.5	401

SZ Series

SUMIKASUPER SZ6709L	115	5.0	--	140	11.0	310
SUMIKASUPER SZ6505HF	130	7.0	9,900	140	11.2	430
SUMIKASUPER SZ6506HF	127	6.1	10,800	140	11.9	360

SR Series

SUMIKASUPER SR1009	146	4.5	11,600	174	12.6	151
SUMIKASUPER SR3003L*	182	3.4	--	246	11.6	--
SUMIKASUPER SR2506	133	7.0	12,900	147	11.7	352

* Properties quantified per ISO test methods.

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